

L Number	Hits	Search Text	DB	Time stamp
1	298253	mask	USPAT; EPO; JPO; DERWENT	2002/04/18 17:32
2	10145	conformable	USPAT; EPO; JPO; DERWENT	2002/04/18 17:32
3	1646757	substrate workpiece wafer	USPAT; EPO; JPO; DERWENT	2002/04/18 17:33
4	613481	deform\$5	USPAT; EPO; JPO; DERWENT	2002/04/18 17:34
5	621248	conformable deform\$5	USPAT; EPO; JPO; DERWENT	2002/04/18 17:34
6	8338	mask and (substrate workpiece wafer) and (conformable deform\$5)	USPAT; EPO; JPO; DERWENT	2002/04/18 17:34
7	48327	electroplat\$3	USPAT; EPO; JPO; DERWENT	2002/04/18 17:34
8	3295	electrolytic adj deposition	USPAT; EPO; JPO; DERWENT	2002/04/18 17:34
9	746	electrolytically adj depositing	USPAT; EPO; JPO; DERWENT	2002/04/18 17:35
10	116	electrolytically adj deposit	USPAT; EPO; JPO; DERWENT	2002/04/18 17:35
11	23714	electrodeposition	USPAT; EPO; JPO; DERWENT	2002/04/18 17:35
12	70237	electroplat\$3 (electrolytic adj deposition) (electrolytically adj depositing) (electrolytically adj deposit) electrodeposition	USPAT; EPO; JPO; DERWENT	2002/04/18 17:35
13	1049	(electroplat\$3 (electrolytic adj deposition) (electrolytically adj depositing) (electrolytically adj deposit) electrodeposition) and (mask and (substrate workpiece wafer) and (conformable deform\$5))	USPAT; EPO; JPO; DERWENT	2002/04/18 17:36
14	118105	mask same (substrate workpiece wafer)	USPAT; EPO; JPO; DERWENT	2002/04/18 17:36
15	662	(mask same (substrate workpiece wafer)) and (conformable deform\$5) and (electroplat\$3 (electrolytic adj deposition) (electrolytically adj depositing) (electrolytically adj deposit) electrodeposition)	USPAT; EPO; JPO; DERWENT	2002/04/18 17:52
16	119319	427/\$.ccls.	USPAT; EPO; JPO; DERWENT	2002/04/18 17:53
17	54	427/\$.ccls. and ((mask same (substrate workpiece wafer)) and (conformable deform\$5) and (electroplat\$3 (electrolytic adj deposition) (electrolytically adj depositing) (electrolytically adj deposit) electrodeposition))	USPAT; EPO; JPO; DERWENT	2002/04/18 18:08
18	32612	205/\$.ccls.	USPAT; EPO; JPO; DERWENT	2002/04/18 18:08

19	34	205/\$.ccls. and ((mask same (substrate workpiece wafer)) and (conformable deform\$5) and (electroplat\$3 (electrolytic adj deposition) (electrolytically adj depositing) (electrolytically adj deposit) electrodeposition))	USPAT; EPO; JPO; DERWENT	2002/04/18 18:08
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